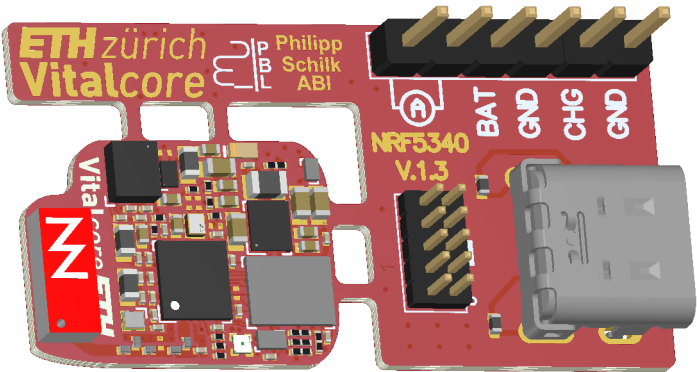
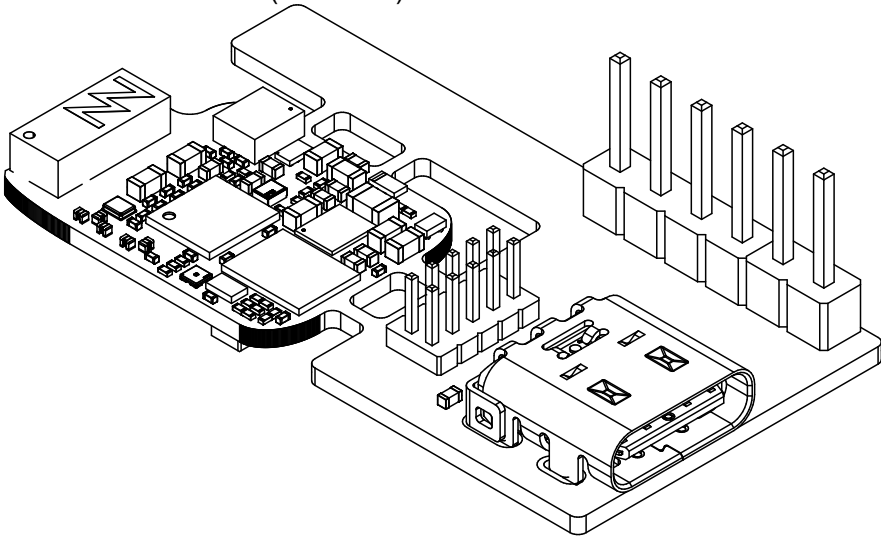


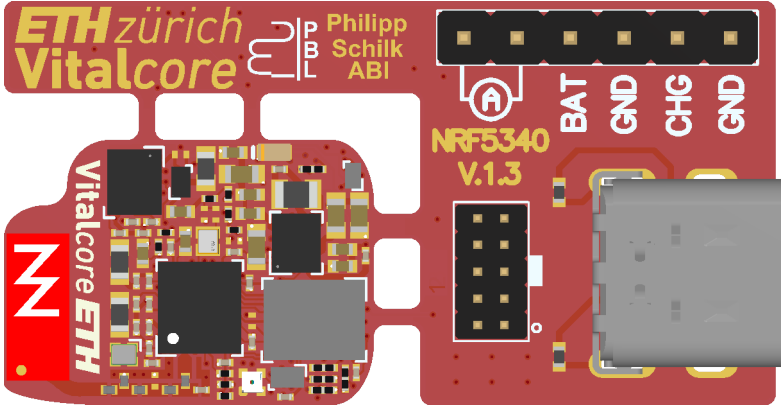
Realistic View



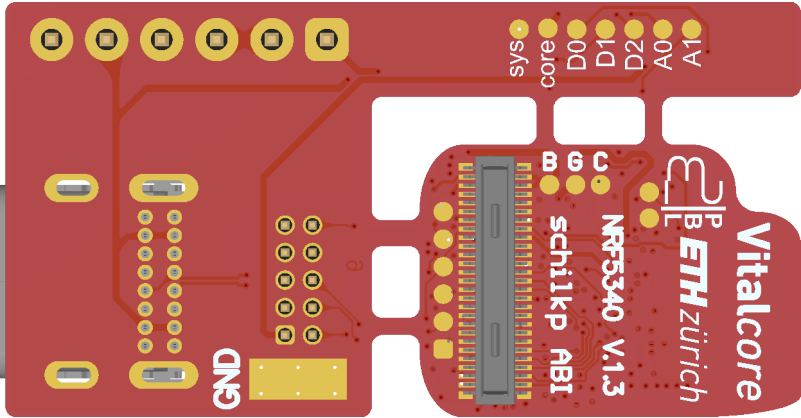
View from Front side (Scale 3:1)



Realistic View



Realistic View



<div><div><div>ETH</div><div>Eidgenössische Technische Hochschule Zürich</div><div>Swiss Federal Institute of Technology Zurich</div></div></div>	Project: VitalCore: NRF5340	
	3D Render	
Laboratory: ETHZ D-ITET PBL	Drawn By: Philipp Schilk, Alfonso Blanco Fontao	
Date: 3/4/2024 2:21 PM		
Revision: 1.3 License: GNU GPL v3	Checked By: Federico Villani, Lukas Schulthess	
Variant: Complete		
File: DOC_3D.PCBDwf	Sheet: 1/1	

A

B

C

D

1

1

2

2

3

3

4

4

Drill Drawing View (Scale 6:1)

36.70mm

19.20mm

12.60mm

17.60mm

0.00mm

Drill Table

Symbol	Count	Hole Size	Plated	Drill Layer Pair
○	160	0.15mm	Plated	Top Layer - Bottom Layer
◇	88	0.15mm	Plated	[UVIA] Top Layer - Int1 (Sign)
⊕	37	0.15mm	Plated	[UVIA] Int4 (Sign) - Bottom Layer
▽	16	0.40mm	Plated	Top Layer - Bottom Layer
□	10	0.65mm	Plated	Top Layer - Bottom Layer
☆	4	0.70mm	Plated	Top Layer - Bottom Layer
⊗	6	1.00mm	Plated	Top Layer - Bottom Layer
	321 Total			

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Variant: Complete

File: DOC_MANUFACTURE.PCBDwf

Project: VitalCore: NRF5340

Manufacturing

Drawn By: Philipp Schilk, Alfonso Blanco Fontao

Checked By: Federico Villani, Lukas Schulthess

Sheet: 1/2

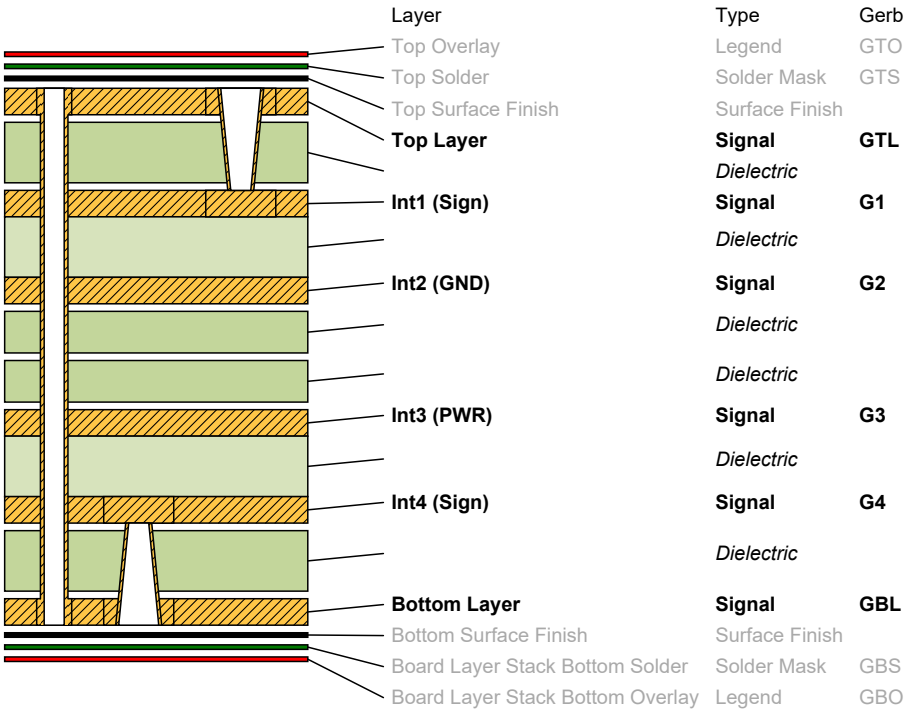
A

B

C

D

Layer Stack Legend



NOTES:

- HDI/Buried Via.
- Via in pad.
- 0.8mm Board: Use PCBWAY standard stackup (see left).
- ENIG finish.
- Red solder mask.

Use standard PCBWAY 6layer/0.8mm stackup:

Thickness	Copper thick (outer/inner)	Layer No.	StackUp	Laminated chart Thickness
0.8mm±0.1mm	1/1oz	L1		Copper 18 um--plating to 35um
				PP 0.11 mm(2116) dielectric constant 4.29 ± (The DK value is not absolute and will vary depending on the base material's models and thickness.)
		L2		
		L3		Core 0.2mm with 1/1 oz Cu
				PP 0.11 mm(2116) dielectric constant 4.29 ± (The DK value is not absolute and will vary depending on the base material's models and thickness.)
		L4		
		L5		Core 0.2mm with 1/1 oz Cu
				PP 0.11 mm(2116) dielectric constant 4.29 ± (The DK value is not absolute and will vary depending on the base material's models and thickness.)
		L6		
				Copper 18 um--plating to 35um

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File: DOC_MANUFACTURE.PCBDwf

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Manufacturing

Drawn By: Philipp Schilk, Alfonso Blanco Fontao
Checked By: Federico Villani, Lukas Schulthess

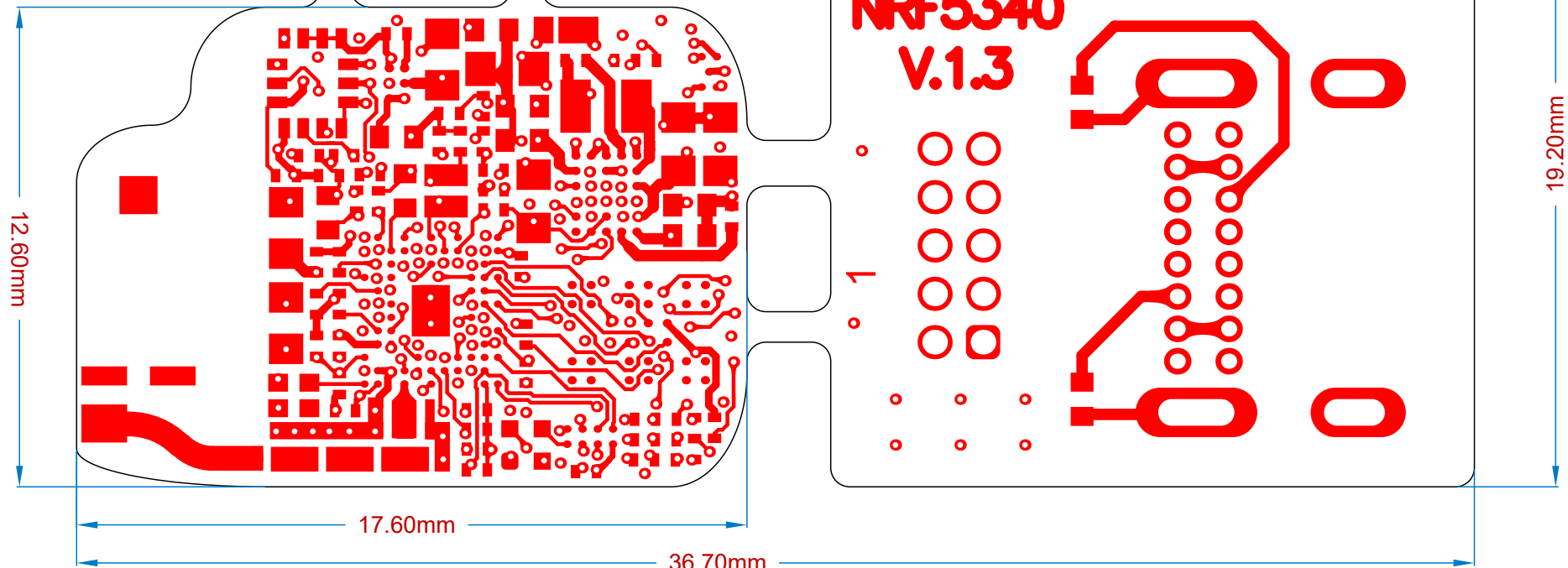
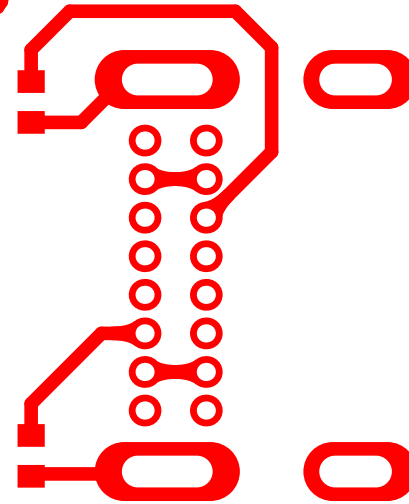
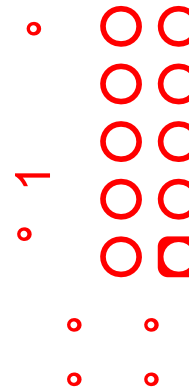
Top Layer (Scale 6:1)

ETH zürich
Vitalcore

Philipp
Schilk
ABI



NRF5340
V.1.3



ETH

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Swiss Federal Institute of Technology Zurich

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Variant: Complete

File: DOC_ART.PCBDwf

Project: VitalCore: NRF5340

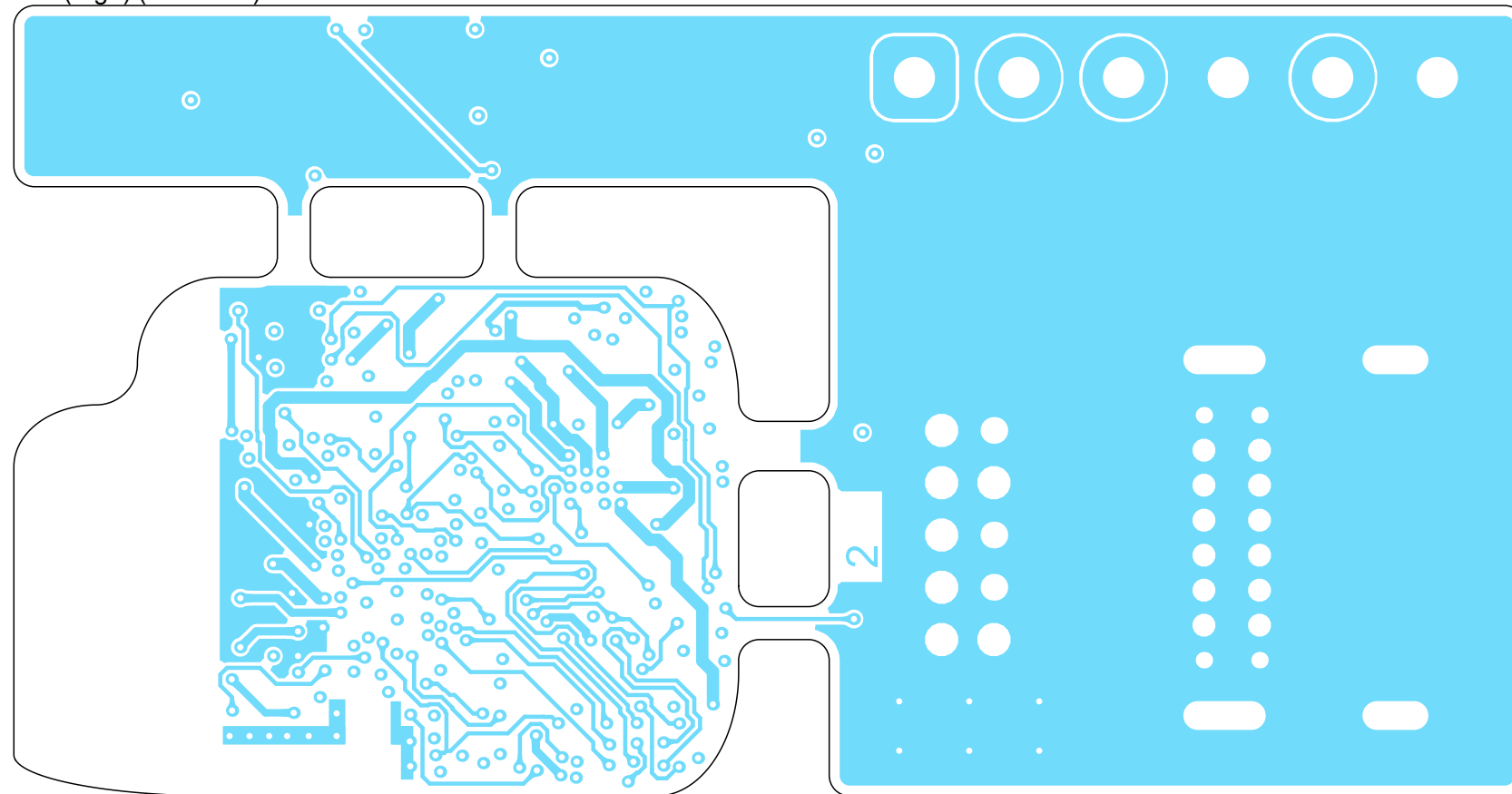
Art

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Sheet: 1/6

Int1 (Sign) (Scale 6:1)



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File: DOC_ART.PCBDwf

Project: VitalCore: NRF5340

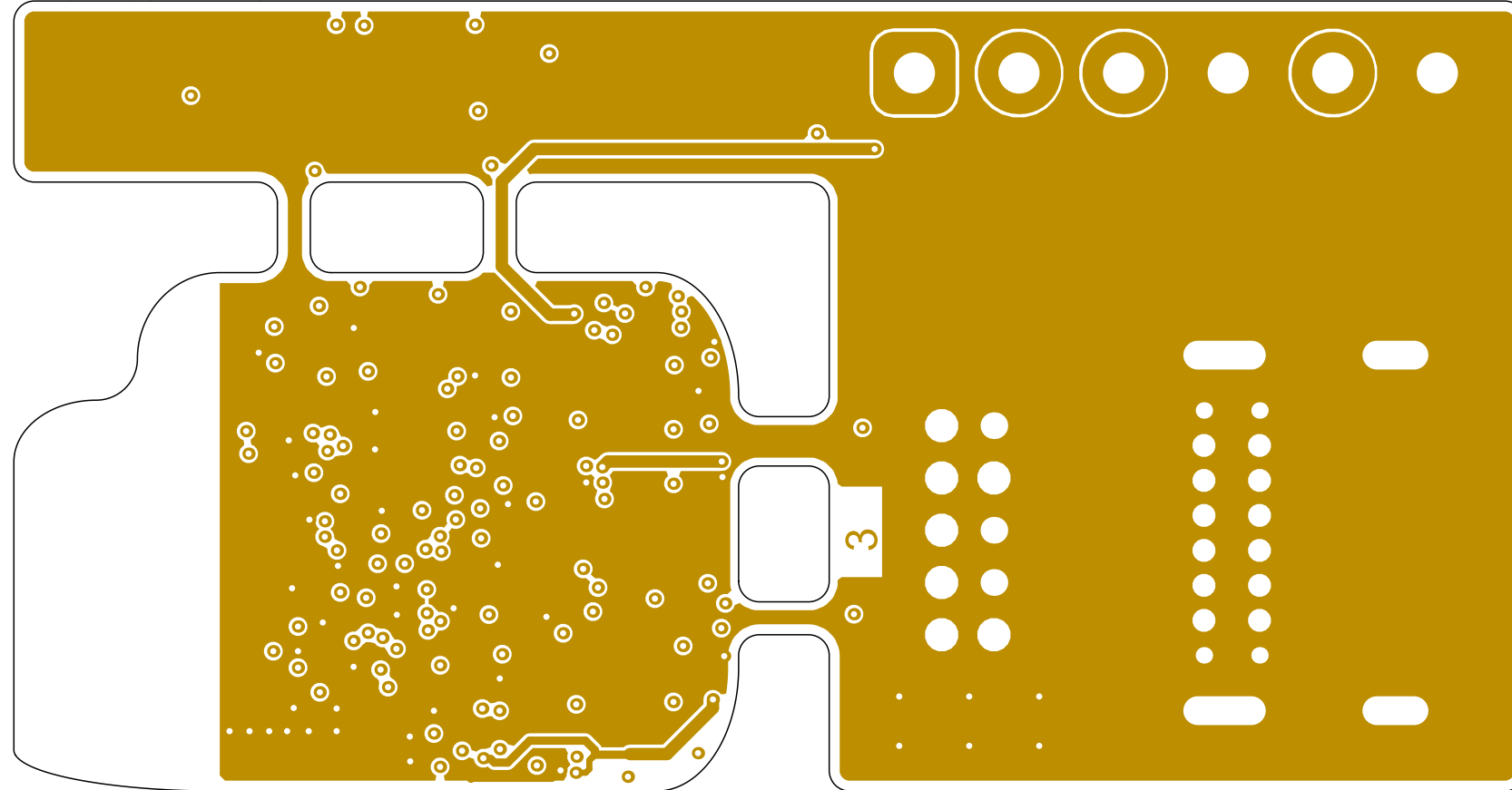
Art

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Sheet: 2/6

Int2 (GND) (Scale 6:1)



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Variant: Complete

File: DOC_ART.PCBDwf

Project: VitalCore: NRF5340

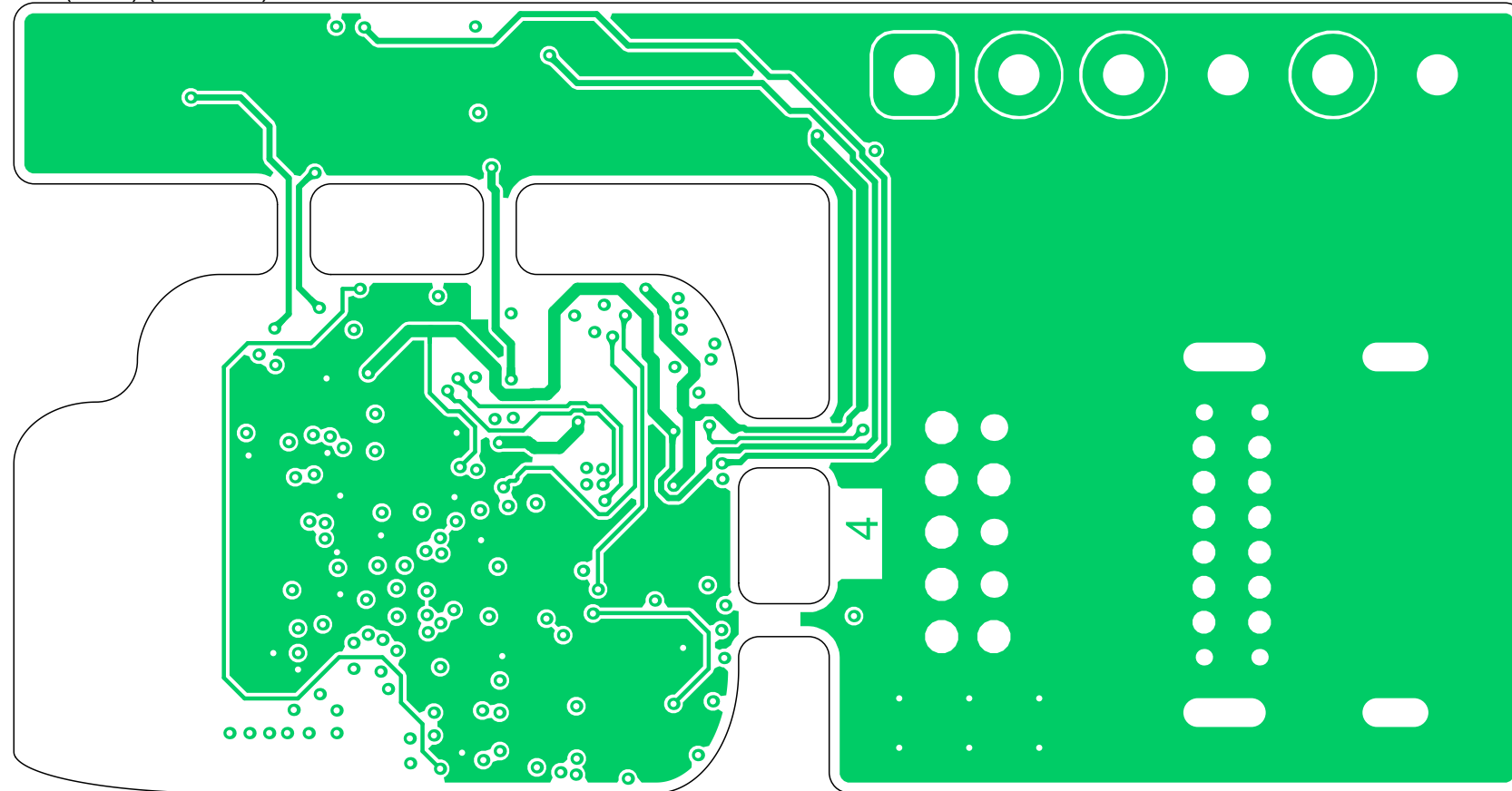
Art

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Sheet: 3/6

Int3 (PWR) (Scale 6:1)



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Variant: Complete

File: DOC_ART.PCBDwf

Project: VitalCore: NRF5340

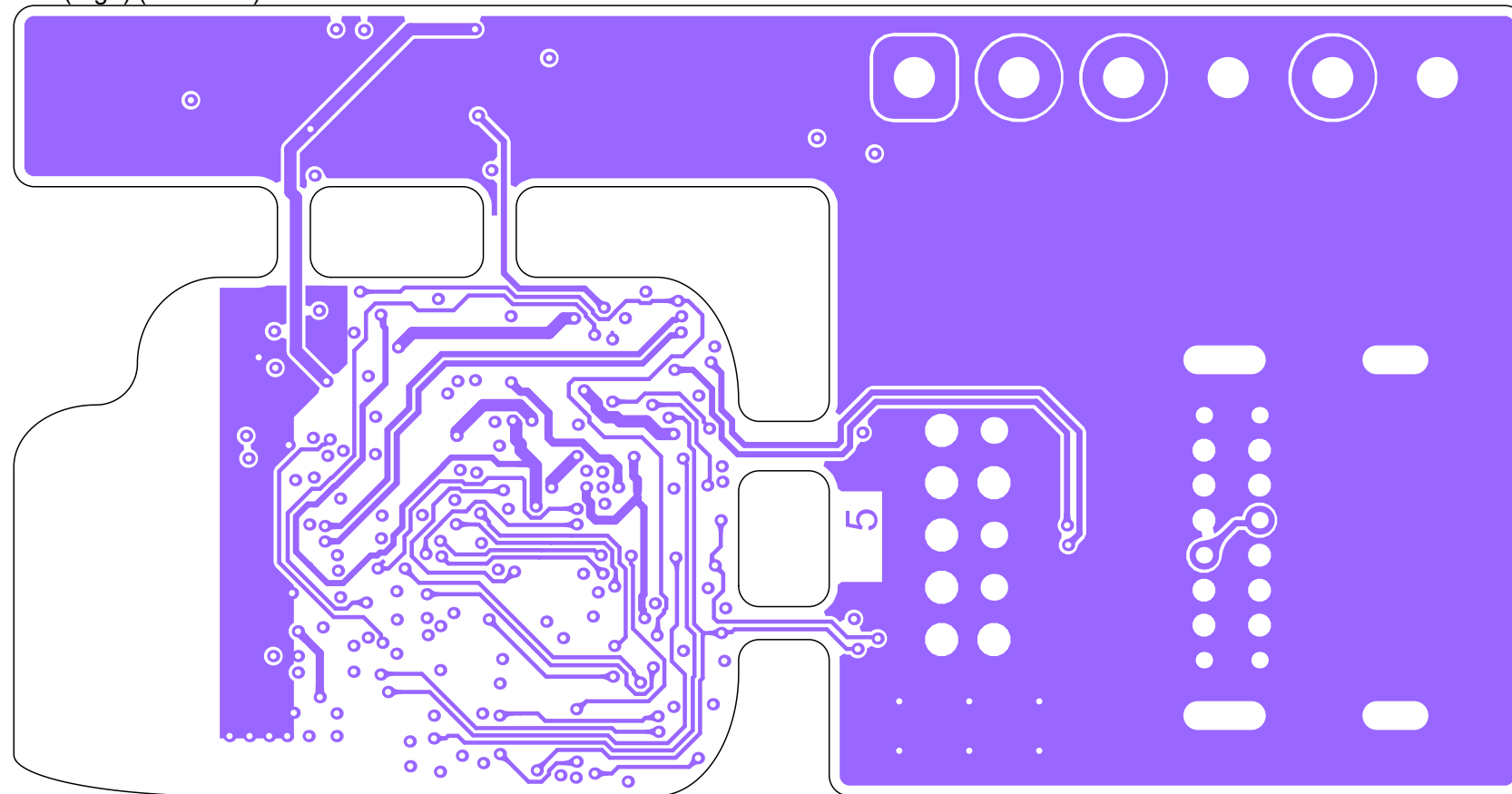
Art

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Sheet: 4/6

Int4 (Sign) (Scale 6:1)



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Variant: Complete

File: DOC_ART.PCBDwf

Project: VitalCore: NRF5340

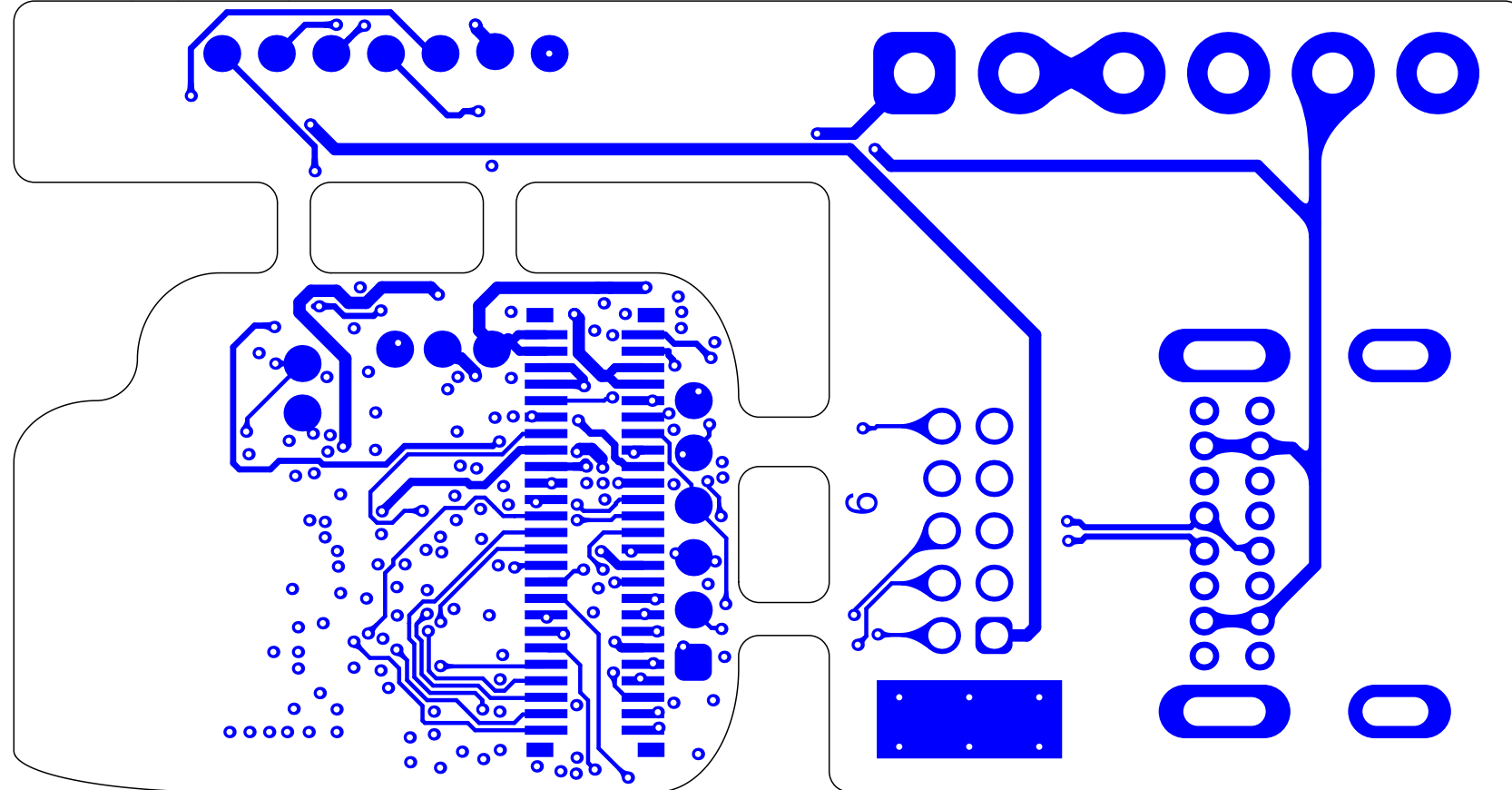
Art

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Sheet: 5/6

Bottom Layer (Scale 6:1)



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Revision: 1.3 License: GNU GPL v3

Variant: Complete

File: DOC_ART.PCBDwf

Project: VitalCore: NRF5340

Art

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Sheet: 6/6